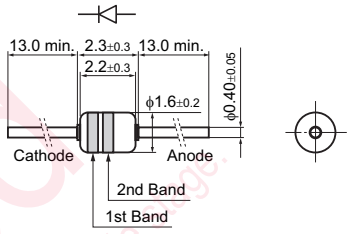
MA2C029

Silicon epitaxial planar type

For reduced voltage and temperature compensation

Unit: mm



DO-34-A1 Package

■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Forward current (Average)	$I_{F(AV)}$	50	mA
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$ *1

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward current	V_{F1}	$I_F = 1.5$ mA		2 *2		V
	V_{F2}	$I_F = 50$ mA			1.1	
Reverse current	I_R	$V_R = 6$ V			10	μA
Temperature coefficient of forward voltage *3	$-\Delta V_F/V_T$	$I_F = 1.5$ mA		2.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_F mesurement. V_F value measured at other temperature must be adjusted to V_F (25°C)

*2:

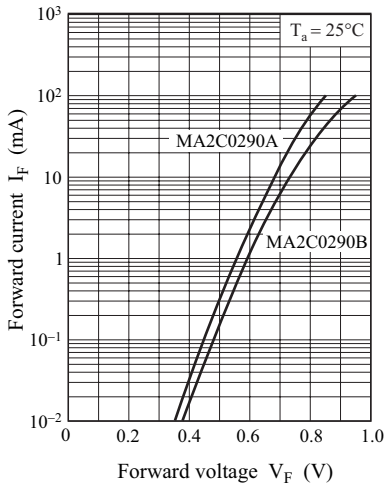
Type	V_F (V)
MA2C0290A	0.56 to 0.61
MA2C0290A1	0.56 to 0.59
MA2C0290A2	0.58 to 0.61
MA2C0290B	0.59 to 0.64
MA2C0290B1	0.59 to 0.62
MA2C0290B2	0.61 to 0.64

*3: $T_j = 25°C$ to 150°C

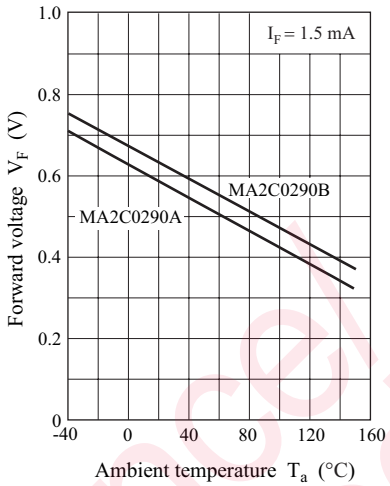
■ Cathode Indication

Type No.	MA2C0290A	MA2C0290A1	MA2C0290A2	MA2C0290B	MA2C0290B1	MA2C0290B2
1st band color	Red	Red	Red	Blue	Blue	Blue
2nd band color	—	Blue	Yellow	—	Blue	Yellow

I_F — V_F



V_F — T_a



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